

*G. James*  
*Reznick A*  
*22/6/02*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Curran, et al. Docket No. ~~11-29038~~ 11-29038  
Serial No: To be Assigned Examiner: TBD  
Conf. No: To be Assigned Art Unit: TBD  
Filed: 10/26/2001  
For: METHOD AND SYSTEM FOR REDUCING THICKNESS OF SPIN-ON GLASS ON SEMICONDUCTOR WAFERS

Assistant Commissioner for Patents  
Washington, DC 20231

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I hereby certify that the above correspondence is being deposited with the U.S. Postal Service with sufficient postage for "Express Mail Post Office to Addressee" service under 37 CFR 1.10 and is addressed to: Assistant Commissioner for Patents, Washington, DC 20231 on 10-26-01.

*Ann Trent*  
Ann Trent

**PRELIMINARY AMENDMENT**

Dear Sir:

Prior to the examination of the above identified application, please amend the specification by inserting before the first line the sentence:

*A1* - This application claims priority under 35 USC § 119(e)(1) of provisional application Serial No. 60/248,170, filed November 13, 2000.

Should the Examiner have any comments or suggestions concerning this application, it is respectfully requested that the Examiner contact the undersigned in order to expeditiously resolve any outstanding issues.

To the extent necessary, Applicants petition for an Extension of Time under 37 CFR 1.136. Please charge any fees in connection with the filing of this paper, including extension of time fees, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,

Peter K. McLarty  
Agent for Applicants  
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